

Postgraduate Studentship in Structural Engineering at The Hong Kong Polytechnic University

An M. Phil postgraduate studentship is available in the Department of Civil and Structural Engineering, The Hong Kong Polytechnic University (PolyU), in the area of fiber-reinforced polymer composites in civil engineering. The student will join a dynamic research group in emerging structural materials and systems led by Prof Jin-Guang Teng and Dr. Jian-Guo Dai. The successful applicant is expected to commence his/her master degree programme at PolyU soon.

This student will be jointly supervised by Dr Jian-Guo Dai (Chief supervisor) and Prof Jin-Guang Teng (Co-supervisor). The project will involve a combined experimental and theoretical study aimed at developing a theoretical model for the long-term performance of FRP-to-concrete interfaces under combined moisture and thermal cycling. If good progress is made, the student has the opportunity of being recommended with priority to apply for the Hong Kong PhD Fellowship (<http://www.polyu.edu.hk/ro/hkphd-fellowship/>) during or after the completion of his/her M. Phil study.

• Expected Qualifications and Attributes

Applicants must possess the following qualifications/attributes:

- (a) A bachelor degree in civil engineering with academic results being within the top 15% (but preferably with the top 10%) of the class from a reputable university.
- (b) A strong interest in pursuing an academic/research career;
- (c) Competency and interest in both theoretical/numerical and experimental work; and
- (d) An English test score acceptable to PolyU [TOEFL: 550 (paper-based); 213 (computer based); 79 (internet-based); IELTS: 6]

Applicants with relevant research experience will be given preference. Research publications will be an important criterion for assessing the research experience and achievement of an applicant.

• Stipend

Each successful applicant will receive a monthly stipend (currently at HK\$ 13,350 per month) for two years, provided satisfactory progress is made.

- **Application Procedure**

If you meet the above requirements and are interested in the studentship, please